

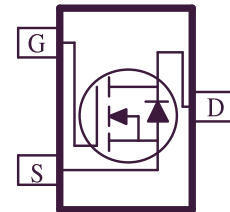
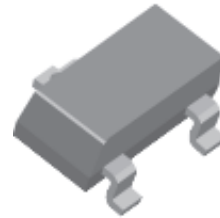
N-Channel 100V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, cellular and cordless telephones.

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
100	0.092 @ $V_{GS} = 10$ V	3.1
	0.099 @ $V_{GS} = 5.5$ V	3.0

- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOT-23 saves board space
- Fast switching speed
- High performance trench technology



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ^a	$T_A = 25^\circ\text{C}$	I_D	3.1	A
Pulsed Drain Current ^b		I_{DM}	± 10	
Continuous Source Current (Diode Conduction) ^a		I_S	1.1	A
Power Dissipation ^a	$T_A = 25^\circ\text{C}$	P_D	1.30	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typ	Max	
Maximum Junction-to-Ambient ^a	$t \leq 10$ sec	R_{thJA}	93	110	$^\circ\text{C/W}$
	Steady State		130	150	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1			V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±8 V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V			1	μA
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 55°C			10	
On-State Drain Current ^A	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	10			A
Drain-Source On-Resistance ^A	r _{DS(on)}	V _{GS} = 10 V, I _D = 0.1 A			92	mΩ
		V _{GS} = 5.5 V, I _D = 0.1 A			99	
Forward Tranconductance ^A	g _{fs}	V _{DS} = 10 V, I _D = 0.1 A		11.3		S
Diode Forward Voltage	V _{SD}	I _S = 0.1 A, V _{GS} = 0 V		0.75		V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = 10 V, V _{GS} = 5.5 V, I _D = 0.1 A		9		nC
Gate-Source Charge	Q _{gs}			2		
Gate-Drain Charge	Q _{gd}			3		
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10 V, R _L = 15 Ω, I _D = 1 A, V _{GEN} = 4.5 V		7		ns
Rise Time	t _r			5		
Turn-Off Delay Time	t _{d(off)}			30		
Fall-Time	t _f			6		

Notes

- Pulse test: $PW \leq 300\mu\text{s}$ duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.